

Docket No.: M4065.0382/P382-A

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Paul A. Farrar et al.

Application No.: 09/940,792

Confirmation No.: 5268

Filed: August 29, 2001

Art Unit: 2815

For:

BURIED CONDUCTOR PATTERNS

FORMED BY SURFACE

TRANSFORMATION OF EMPTY SPACES

IN SOLID STATE MATERIALS

Examiner: E. C. H. Lee

INFORMATION DISCLOSURE STATEMENT (IDS)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Pursuant to 37 CFR 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO/SB/08. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement, pursuant to 37 CFR 1.114(c), accompanies the Request for Continued Examination (37 CFR 1.114) submitted herewith.

Applicant has not submitted copies of each cited U.S. patent and U.S. patent application as required by 37 CFR 1.98(a)(2)(i), amended October 2004, as the U.S.

Application No.: 09/940,792 Docket No.: M4065.0382/P382-A

Patent and Trademark Office has waived this requirement for all U.S. patent applications. Applicant submits herewith copies of foreign and non-patents in accordance with 37 CFR 1.98(a)(2).

In accordance with 37 CFR 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 CFR 1.56(a) exists. In accordance with 37 CFR 1.97(h), the filing of this Information Disclosure statement shall not be construed to be an admission that any patent, publication or other information referred to therein is "prior art" for this invention unless specifically designated as such.

It is submitted that the Information Disclosure Statement is in compliance with 37 CFR 1.98 and the Examiner is respectfully requested to consider the listed references.

The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1073, under Order No. M4065.0382/P382-A. A duplicate copy of this paper is enclosed.

Dated: March 27, 2006

Respectfull submitted,

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Suh	Substitute for form 1449A/B/PTO		Complete if Known		
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S	STATEMENT BY APPLICANT			First Named Inventor	Paul A. Farrar et al.
	.,			Art Unit	2815
	(Use as many sheets as necessary)			Examiner Name	E.C.H. Lee
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PTO/SB/08a/b (07-05)
Approved for use through 07/31/2006. OMB 0651-0031
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